



NIC COMPONENTS CORP.

70 Maxess Road • Melville, New York 11747

(516) 396-7500 • Fax (516) 396-7575

FEATURES

- Glass Passivated Junction
- High Temperature Metallurgical Bonded Construction
- Molded Plastic Case, Over Glass, Meets UL-94V-0 Flammability Classification
- Capable Of Meeting Environmental Testing Per MIL-STD-19500
- Flow And Reflow Soldering Compatible

PRODUCT SPECIFICATION

NIC P/N: NRF4001TR

DESC: SURFACE MOUNT (MELF) SILICON RECTIFIER DIODE

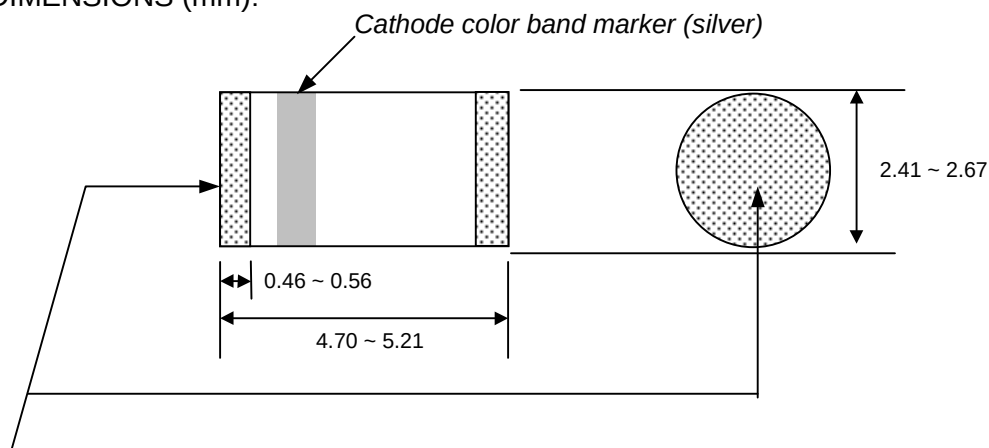
SPECIFICATIONS:

1. OPERATING TEMPERATURE RANGE T_J , T_{STG} :	-65°C ~ +175°C
2. MAXIMUM RECURRENT PEAK RECOVERY VOLTAGE:	50V
3. MAXIMUM RMS VOLTAGE:	35V
4. MAXIMUM DC BLOCKING VOLTAGE:	50VDC
5. MAXIMUM AVERAGE FORWARD CURRENT ($T_T=+75^\circ\text{C}$):	1.0A
6. PEAK FORWARD SURGE CURRENT, I_{FM} (SURGE): (8.3ms Single Half Sine Wave Superimposed On Rated Load, JEDEC Method, $T_A=+75^\circ\text{C}$)	30A
7. MAXIMUM INSTANTANEOUS FORWARD VOLTAGE AT 1.0A:	1.1V
8. MAXIMUM FULL LOAD REVERSE CURRENT: (Full Cycle Average at $T_A=+75^\circ\text{C}$)	30μA
9. MAXIMUM DC REVERSE CURRENT (At Rated DC Blocking Voltage):	10μA (+25°C) 50μA (+125°C)
10. TYPICAL JUNCTION CAPACITANCE (1MHz, 4.0VDC Bias):	15pF
11. MAXIMUM THERMAL RESISTANCE R_{thJL} (SEE NOTE):	30°C/W
R_{thJA} (SEE NOTE):	75°C/W

NOTE: R_{thJL} = Thermal resistance junction to terminal, 6.0mm² copper pads to each terminal.

R_{thJA} = Thermal resistance junction to ambient, 6.0mm² copper pads to each terminal.

12. DIMENSIONS (mm):



TERMINATION: SOLDER PLATE OVER NICKEL BARRIER OVER COPPER BASE METALLIZATION. MEETS SOLDERABILITY PER MIL-STD-202F, METHOD 208.



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PRODUCT SPECIFICATION

NIC P/N: NRF4002TR

DESC: SURFACE MOUNT (MELF) SILICON RECTIFIER DIODE

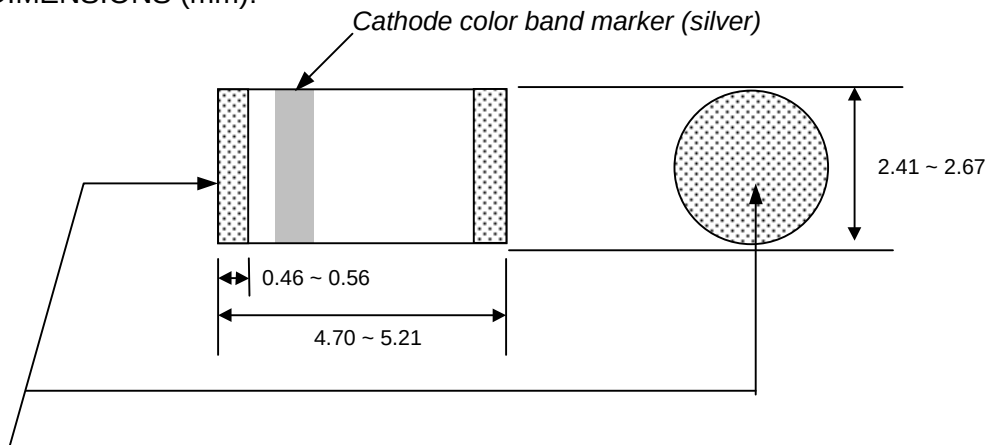
SPECIFICATIONS:

1. OPERATING TEMPERATURE RANGE T_J , T_{STG} :	-65°C ~ +175°C
2. MAXIMUM RECURRENT PEAK RECOVERY VOLTAGE:	100V
3. MAXIMUM RMS VOLTAGE:	70V
4. MAXIMUM DC BLOCKING VOLTAGE:	100VDC
5. MAXIMUM AVERAGE FORWARD CURRENT ($T_T=+75^\circ\text{C}$):	1.0A
6. PEAK FORWARD SURGE CURRENT, I_{FM} (SURGE): (8.3ms Single Half Sine Wave Superimposed On Rated Load, JEDEC Method, $T_A=+75^\circ\text{C}$)	30A
7. MAXIMUM INSTANTANEOUS FORWARD VOLTAGE AT 1.0A:	1.1V
8. MAXIMUM FULL LOAD REVERSE CURRENT: (Full Cycle Average at $T_A=+75^\circ\text{C}$)	30 μA
9. MAXIMUM DC REVERSE CURRENT (At Rated DC Blocking Voltage):	10 μA (+25°C) 50 μA (+125°C)
10. TYPICAL JUNCTION CAPACITANCE (1MHz, 4.0VDC Bias):	15pF
11. MAXIMUM THERMAL RESISTANCE R_{thJL} (SEE NOTE):	30°C/W
R_{thJA} (SEE NOTE):	75°C/W

NOTE: R_{thJL} = Thermal resistance junction to terminal, 6.0mm² copper pads to each terminal.

R_{thJA} = Thermal resistance junction to ambient, 6.0mm² copper pads to each terminal.

12. DIMENSIONS (mm):



TERMINATION: SOLDER PLATE OVER NICKEL BARRIER OVER COPPER BASE METALLIZATION. MEETS SOLDERABILITY PER MIL-STD-202F, METHOD 208.



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PRODUCT SPECIFICATION

NIC P/N: NRF4003TR

DESC: SURFACE MOUNT (MELF) SILICON RECTIFIER DIODE

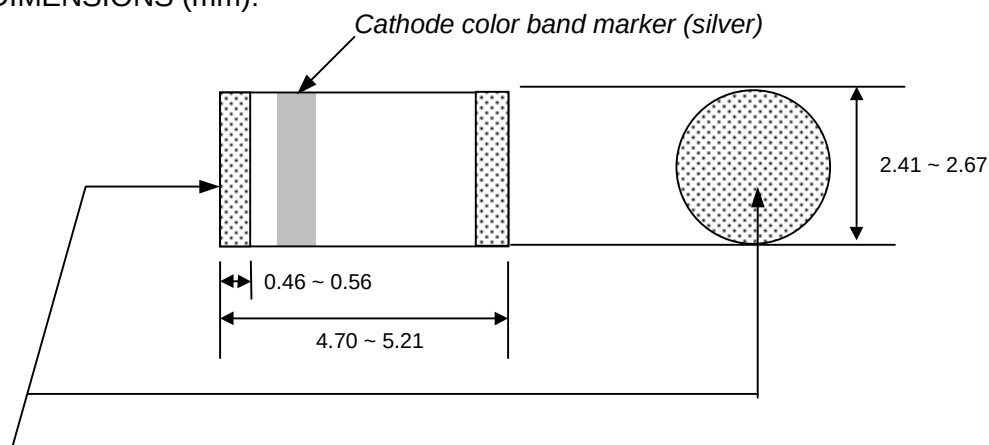
SPECIFICATIONS:

1. OPERATING TEMPERATURE RANGE T_J , T_{STG} :	-65°C ~ +175°C
2. MAXIMUM RECURRENT PEAK RECOVERY VOLTAGE:	200V
3. MAXIMUM RMS VOLTAGE:	140V
4. MAXIMUM DC BLOCKING VOLTAGE:	200VDC
5. MAXIMUM AVERAGE FORWARD CURRENT ($T_T=+75^\circ\text{C}$):	1.0A
6. PEAK FORWARD SURGE CURRENT, I_{FM} (SURGE): (8.3mS Single Half Sine Wave Superimposed On Rated Load, JEDEC Method, $T_A=+75^\circ\text{C}$)	30A
7. MAXIMUM INSTANTANEOUS FORWARD VOLTAGE AT 1.0A:	1.1V
8. MAXIMUM FULL LOAD REVERSE CURRENT: (Full Cycle Average at $T_A=+75^\circ\text{C}$)	30μA
9. MAXIMUM DC REVERSE CURRENT (At Rated DC Blocking Voltage):	10μA (+25°C) 50μA (+125°C)
10. TYPICAL JUNCTION CAPACITANCE (1MHz, 4.0VDC Bias):	15pF
11. MAXIMUM THERMAL RESISTANCE R_{thJL} (SEE NOTE):	30°C/W
R_{thJA} (SEE NOTE):	75°C/W

NOTE: R_{thJL} = Thermal resistance junction to terminal, 6.0mm² copper pads to each terminal.

R_{thJA} = Thermal resistance junction to ambient, 6.0mm² copper pads to each terminal.

12. DIMENSIONS (mm):



TERMINATION: SOLDER PLATE OVER NICKEL BARRIER OVER COPPER BASE METALLIZATION. MEETS SOLDERABILITY PER MIL-STD-202F, METHOD 208.



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PRODUCT SPECIFICATION

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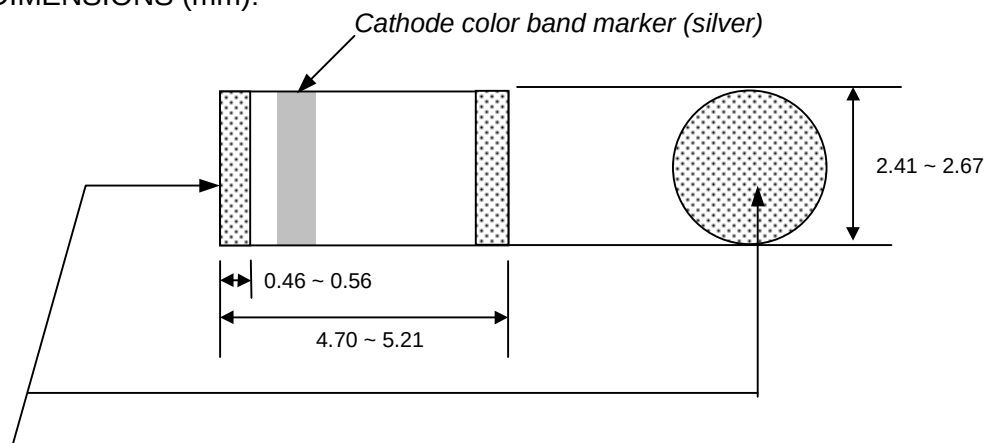
DESC: SURFACE MOUNT (MELF) SILICON RECTIFIER DIODE

SPECIFICATIONS:

1. OPERATING TEMPERATURE RANGE T_J , T_{STG} :	-65°C ~ +175°C
2. MAXIMUM RECURRENT PEAK RECOVERY VOLTAGE:	400V
3. MAXIMUM RMS VOLTAGE:	280V
4. MAXIMUM DC BLOCKING VOLTAGE:	400VDC
5. MAXIMUM AVERAGE FORWARD CURRENT ($T_J=+75^{\circ}\text{C}$):	1.0A
6. PEAK FORWARD SURGE CURRENT, I_{FM} (SURGE): (8.3ms Single Half Sine Wave Superimposed On Rated Load, JEDEC Method, $T_A=+75^{\circ}\text{C}$)	30A
7. MAXIMUM INSTANTANEOUS FORWARD VOLTAGE AT 1.0A:	1.1V
8. MAXIMUM FULL LOAD REVERSE CURRENT: (Full Cycle Average at $T_A=+75^{\circ}\text{C}$)	30μA
9. MAXIMUM DC REVERSE CURRENT (At Rated DC Blocking Voltage):	10μA (+25°C) 50μA (+125°C)
10. TYPICAL JUNCTION CAPACITANCE (1MHz, 4.0VDC Bias):	15pF
11. MAXIMUM THERMAL RESISTANCE R_{thJL} (SEE NOTE):	30°C/W
R_{thJA} (SEE NOTE):	75°C/W

NOTE: R_{thJL} = Thermal resistance junction to terminal, 6.0mm² copper pads to each terminal.
 R_{thJA} = Thermal resistance junction to ambient, 6.0mm² copper pads to each terminal.

12. DIMENSIONS (mm):



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PRODUCT SPECIFICATION

NIC P/N: NRF4005TR

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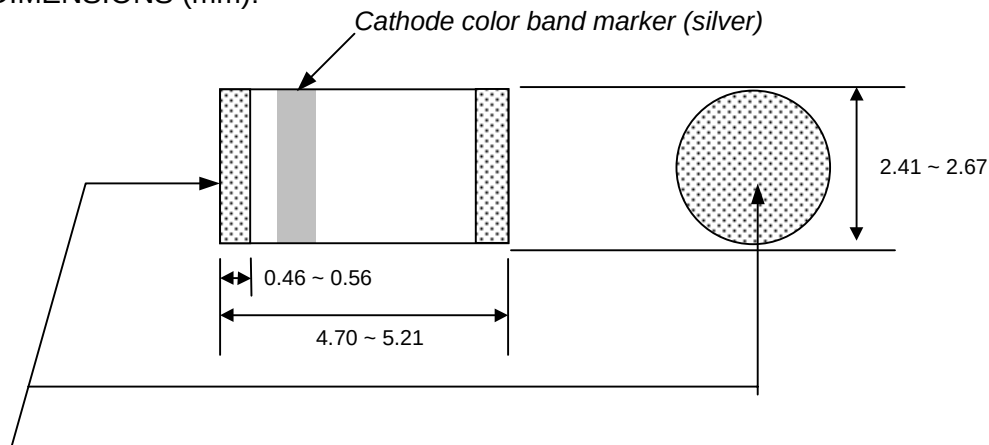
SPECIFICATIONS:

1. OPERATING TEMPERATURE RANGE T_J , T_{STG} :	-65°C ~ +175°C
2. MAXIMUM RECURRENT PEAK RECOVERY VOLTAGE:	600V
3. MAXIMUM RMS VOLTAGE:	420V
4. MAXIMUM DC BLOCKING VOLTAGE:	600VDC
5. MAXIMUM AVERAGE FORWARD CURRENT ($T_T=+75^\circ\text{C}$):	1.0A
6. PEAK FORWARD SURGE CURRENT, I_{FM} (SURGE): (8.3ms Single Half Sine Wave Superimposed On Rated Load, JEDEC Method, $T_A=+75^\circ\text{C}$)	30A
7. MAXIMUM INSTANTANEOUS FORWARD VOLTAGE AT 1.0A:	1.1V
8. MAXIMUM FULL LOAD REVERSE CURRENT: (Full Cycle Average at $T_A=+75^\circ\text{C}$)	30μA
9. MAXIMUM DC REVERSE CURRENT (At Rated DC Blocking Voltage):	10μA (+25°C) 50μA (+125°C)
10. TYPICAL JUNCTION CAPACITANCE (1MHz, 4.0VDC Bias):	15pF
11. MAXIMUM THERMAL RESISTANCE R_{thJL} (SEE NOTE):	30°C/W
R_{thJA} (SEE NOTE):	75°C/W

NOTE: R_{thJL} = Thermal resistance junction to terminal, 6.0mm² copper pads to each terminal.

R_{thJA} = Thermal resistance junction to ambient, 6.0mm² copper pads to each terminal.

12. DIMENSIONS (mm):



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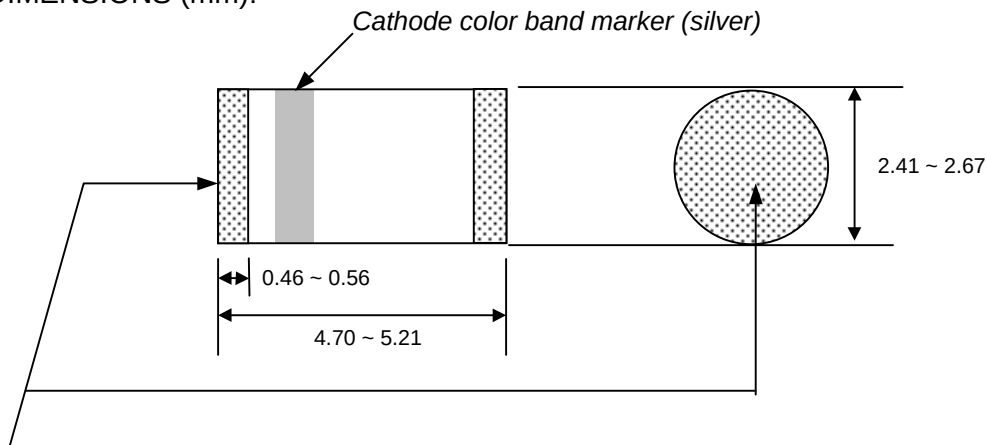
SPECIFICATIONS:

1. OPERATING TEMPERATURE RANGE T_J , T_{STG} :	-65°C ~ +175°C
2. MAXIMUM RECURRENT PEAK RECOVERY VOLTAGE:	800V
3. MAXIMUM RMS VOLTAGE:	560V
4. MAXIMUM DC BLOCKING VOLTAGE:	800VDC
5. MAXIMUM AVERAGE FORWARD CURRENT ($T_T=+75^{\circ}\text{C}$):	1.0A
6. PEAK FORWARD SURGE CURRENT, I_{FM} (SURGE): (8.3mS Single Half Sine Wave Superimposed On Rated Load, JEDEC Method, $T_A=+75^{\circ}\text{C}$)	30A
7. MAXIMUM INSTANTANEOUS FORWARD VOLTAGE AT 1.0A:	1.1V
8. MAXIMUM FULL LOAD REVERSE CURRENT: (Full Cycle Average at $T_A=+75^{\circ}\text{C}$)	30μA
9. MAXIMUM DC REVERSE CURRENT (At Rated DC Blocking Voltage):	10μA (+25°C) 50μA (+125°C)
10. TYPICAL JUNCTION CAPACITANCE (1MHz, 4.0VDC Bias):	15pF
11. MAXIMUM THERMAL RESISTANCE R_{thJL} (SEE NOTE):	30°C/W
R_{thJA} (SEE NOTE):	75°C/W

NOTE: R_{thJL} = Thermal resistance junction to terminal, 6.0mm² copper pads to each terminal.

R_{thJA} = Thermal resistance junction to ambient, 6.0mm² copper pads to each terminal.

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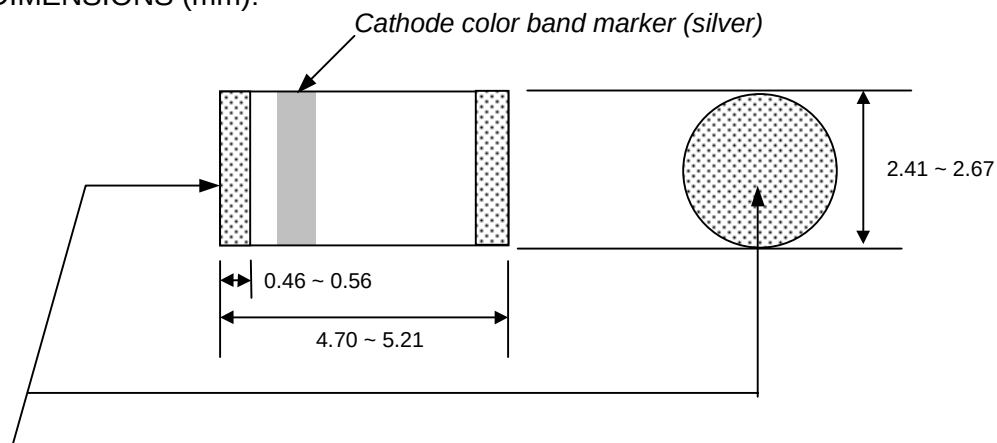
DESC: SURFACE MOUNT (MELF) SILICON RECTIFIER DIODE

SPECIFICATIONS:

1. OPERATING TEMPERATURE RANGE T_J , T_{STG} :	-65°C ~ +175°C
2. MAXIMUM RECURRENT PEAK RECOVERY VOLTAGE:	1000V
3. MAXIMUM RMS VOLTAGE:	700V
4. MAXIMUM DC BLOCKING VOLTAGE:	1000VDC
5. MAXIMUM AVERAGE FORWARD CURRENT ($T_T=+75^{\circ}\text{C}$):	1.0A
6. PEAK FORWARD SURGE CURRENT, I_{FM} (SURGE): (8.3mS Single Half Sine Wave Superimposed On Rated Load, JEDEC Method, $T_A=+75^{\circ}\text{C}$)	30A
7. MAXIMUM INSTANTANEOUS FORWARD VOLTAGE AT 1.0A:	1.1V
8. MAXIMUM FULL LOAD REVERSE CURRENT: (Full Cycle Average at $T_A=+75^{\circ}\text{C}$)	30μA
9. MAXIMUM DC REVERSE CURRENT (At Rated DC Blocking Voltage):	10μA (+25°C) 50μA (+125°C)
10. TYPICAL JUNCTION CAPACITANCE (1MHz, 4.0VDC Bias):	15pF
11. MAXIMUM THERMAL RESISTANCE R_{thJL} (SEE NOTE):	30°C/W
R_{thJA} (SEE NOTE):	75°C/W

NOTE: R_{thJL} = Thermal resistance junction to terminal, 6.0mm² copper pads to each terminal.
 R_{thJA} = Thermal resistance junction to ambient, 6.0mm² copper pads to each terminal.

12. DIMENSIONS (mm):



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